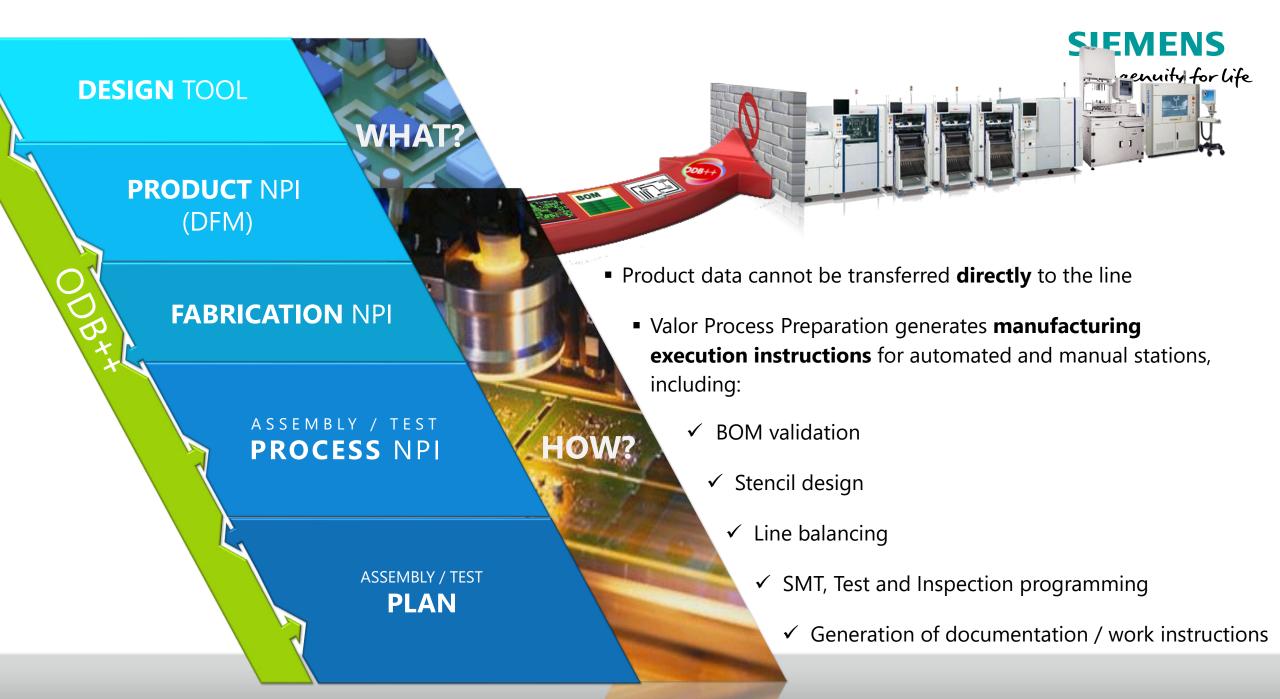




# **valor Process Preparation**





# A complete **ANALYSIS**, **MODELING** and **SIMULATION** environment for maximizing the efficiency of the design-to-manufacturing flow

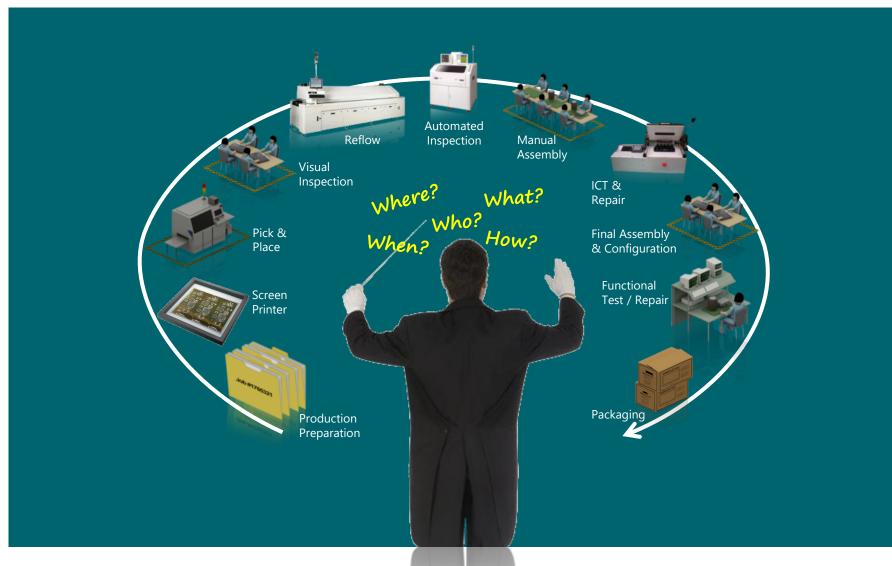


#### **Accelerate NPI**

- ✓ Increase engineering efficiency by using a single tool for all process engineering tasks
- ✓ Eliminate redundant preparation work with Learning Libraries (machine shapes, rotation etc.)
- ✓ Increase efficiency through automation and use of templates (for work instructions, data import parsers, etc.)

#### **Increase line utilization**

 Maximize off-line preparation to eliminate on-line trial and error delays



# A complete **ANALYSIS**, **MODELING** and **SIMULATION** environment for maximizing the efficiency of the design-to-manufacturing flow

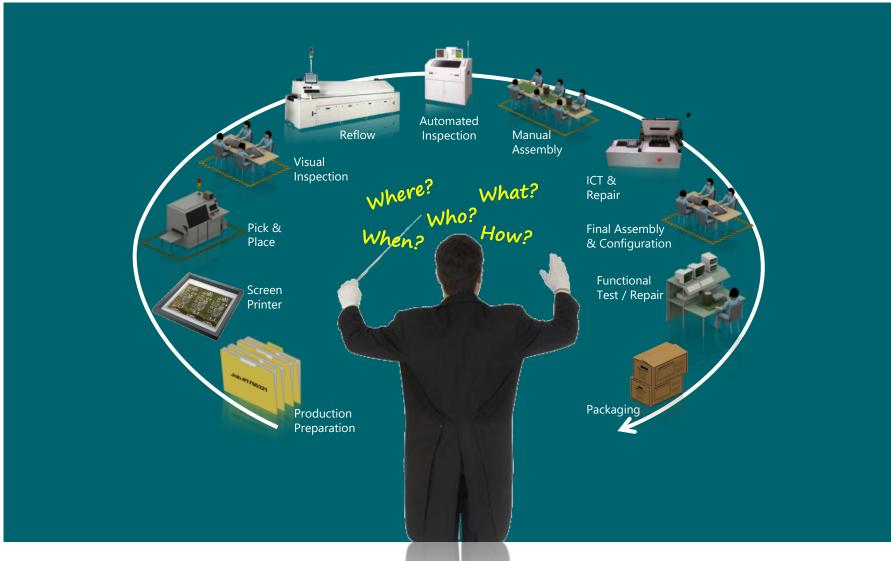


#### **Preserve manufacturing know-how**

- Consolidate organizational bestpractice flows
- Centralized part libraries incl. rotation neutralization and machine shapes
- Custom data preparation flows can be defined, enforced, and re-used

#### **Product portability**

✓ Leverage ODB++ to seamlessly move production
 between lines and factories – eliminate engineering time and increase quality of end product



#### **Customer testimonials**





- ✓ Reduced line setup time by 70%
- ✓ Machine uptime increased by 50%
- ✓ Changeover time reduced from 50 minutes to 13 minutes
- ✓ Annual savings of \$1.4M



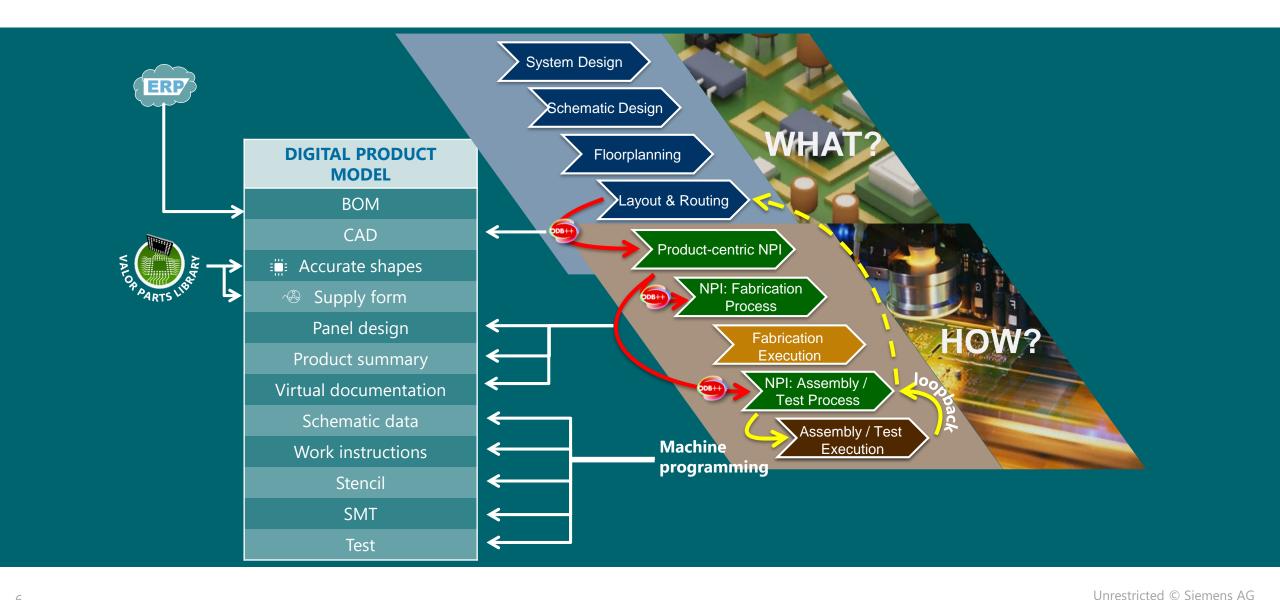
**24h NPI Express** – Using Valor tools in Germany to prepare work orders for production in the US – saving time and implementing "follow the sun" methodology



Time from BOM/AVL to production-ready programs and documentation reduced from 3-5 days to 1-2 days

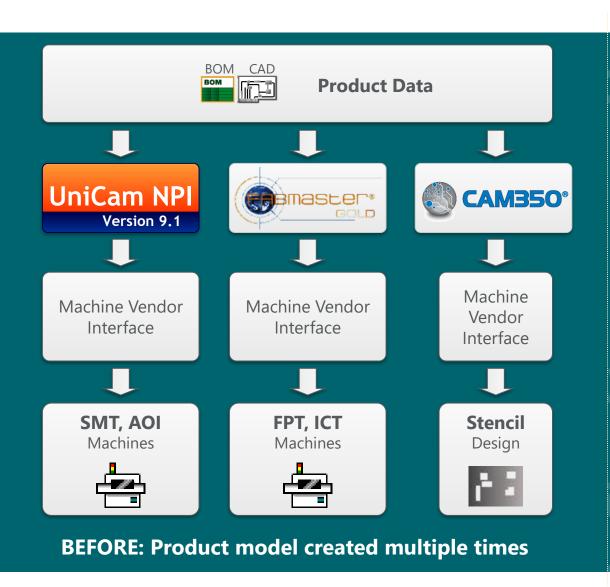
### **Building the digital product model**

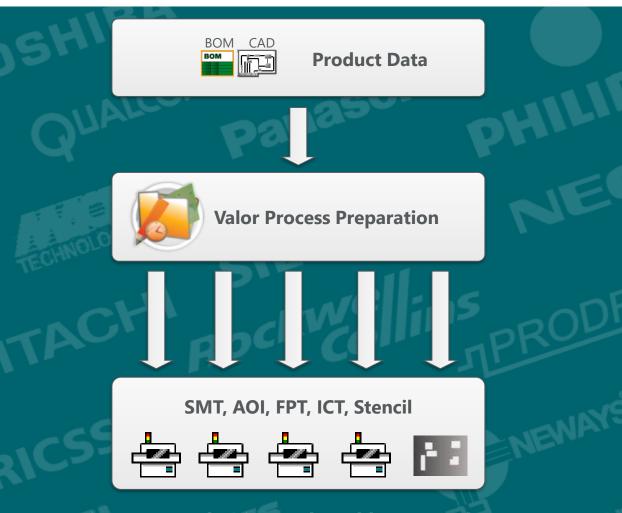




### Harmonized process through a single engineering tool



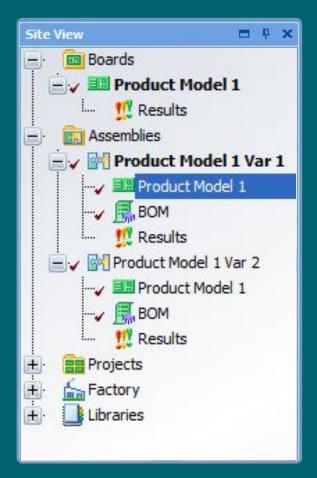




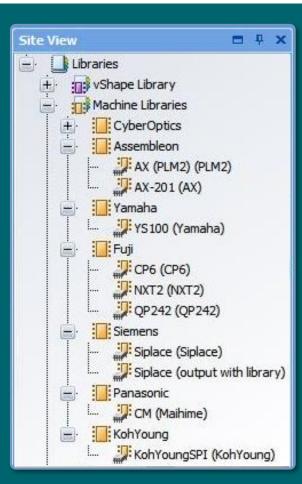
**AFTER: Time-to-production reduced by more than 20%** 

# Single data model covers multiple processes and vendor platforms

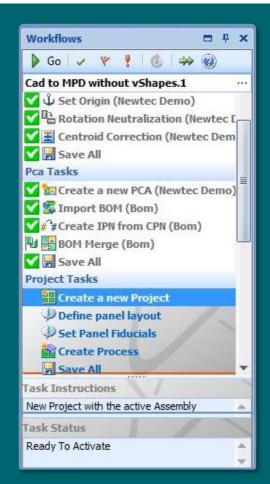




Hierarchical view of assemblies, Including support for multiple instances



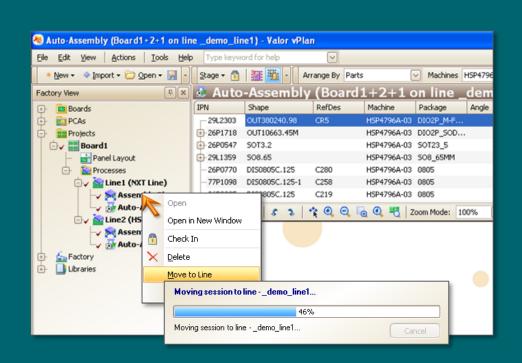
Machine shapes can be generated on demand

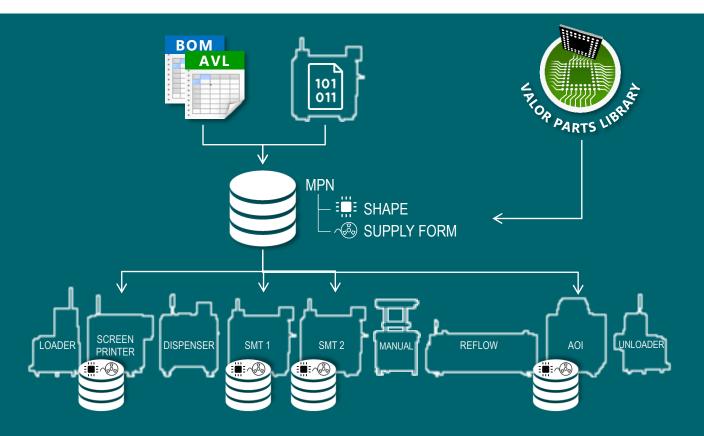


Customizable workflows allow multiple users to share projects and track their status

# Optimize SMT program portability with patented machine shape auto-generation







- Part libraries can be created for each machine directly from the Master Parts Library
- Users can create/modify custom parameters to enhance part/shape data
- Native machine programs can also be imported and quickly converted into alternate machine formats

### **Enable simple work-order portability**

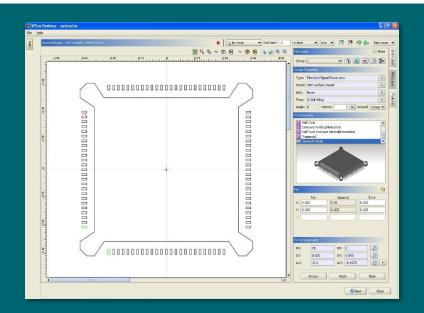




- Single product model can drive all manufacturing of a product worldwide
- Product NPI tasks can be done once at corp. competence centers
- Only process NPI needs to be repeated at each mfg. environment.

#### **Valor Parts Library (VPL)**



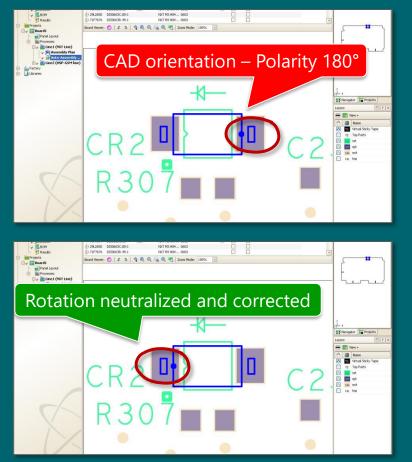


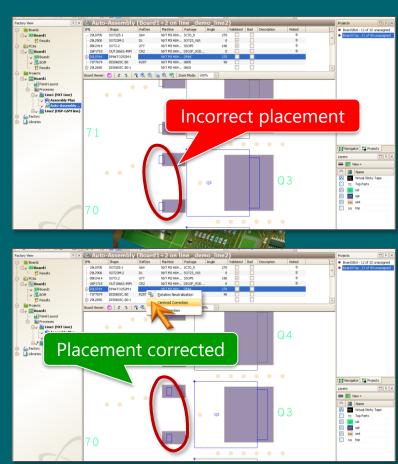
- ISO9001-certified library covering over 35 million part numbers
  - ✓ Accurate shape data
  - ✓ Pin contact area
  - ✓ Component classification (JEDEC)
- Enables accurate virtual-prototype build

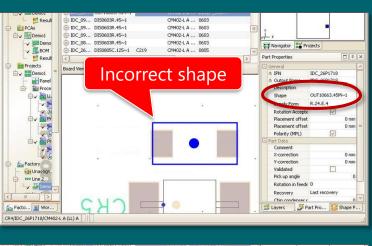
	Item	CPN	Manufacturer 1	MPN	VPL-Package	
1	1	G8316005-244	KEMET	C1210C22K5RAC-LWR	DSO-C2/X-L60W32T25	
2			WALSIN	1210B22K5KKCT-CRM	DSO-C2/X-L60W31T3	
2			AVX	10125C224KATA2A-KOL	DSO-C2/X-L64W25T3	

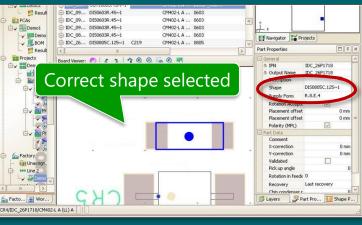
Shapes of alternate parts in the AVL can be easily compared for inconsistencies (example: the parts above provide the same electrical function, but require different pad layouts)

# "Virtual Sticky Tape" – SIEMENS Improve SMT productivity with offline placement simulation for life





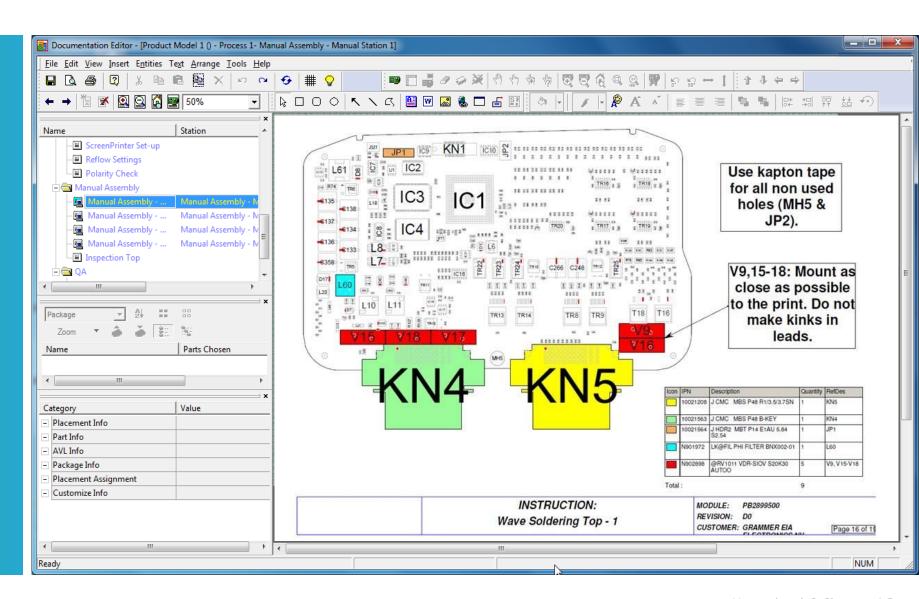




#### **Documentation creation**



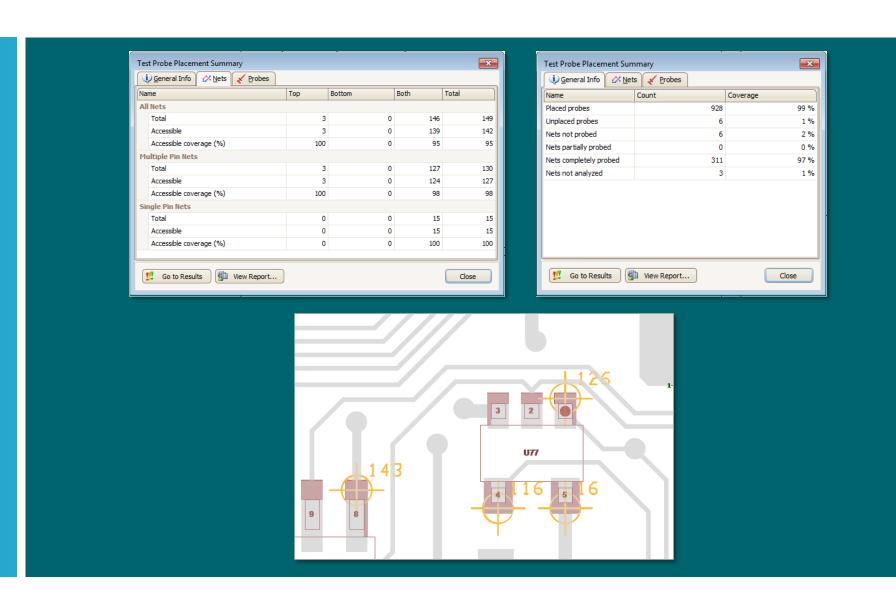
- Built-in and user-defined templates for static and interactive documentation
- Include any design, product model, SMT, Test, and other production information
- Can include embedded images and files (e.g. JPG, PDF)



### Complete testability analysis (DFT) of PCAs



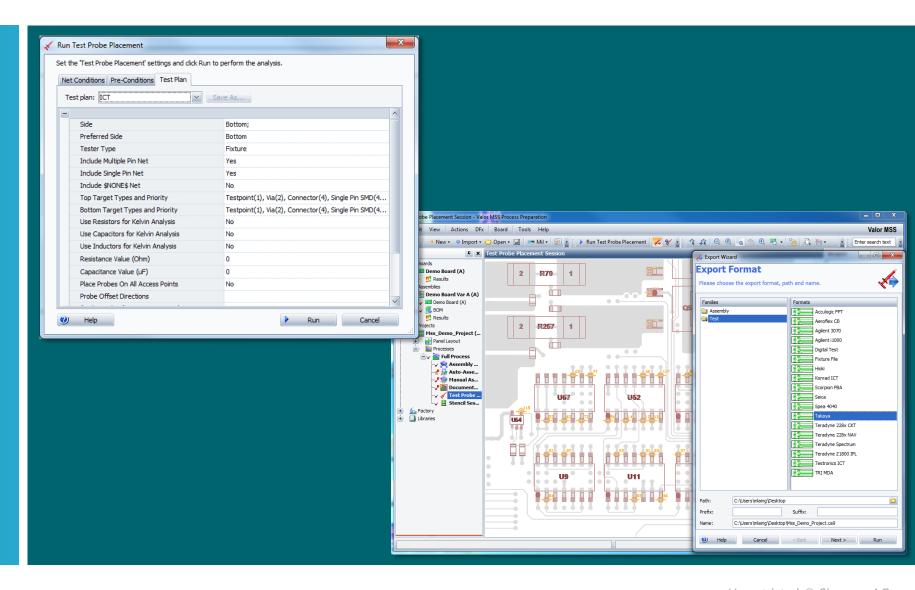
- Identification of high risk areas
- Feedback to design about inaccessible points
- Comprehensive yield analysis to quantify testability



### **Tester and inspection programming**

SIEMENS
Ingenuity for life

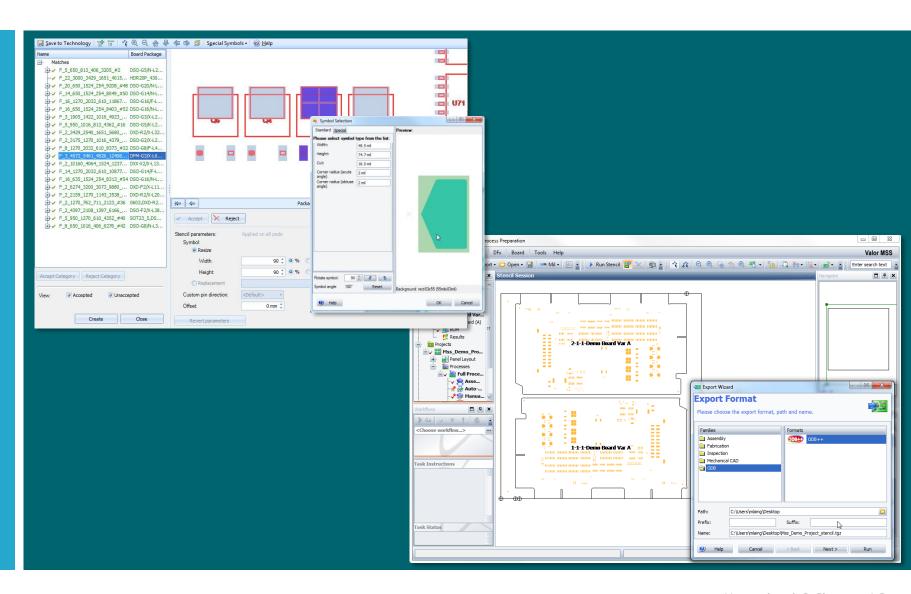
- Automated test probe selection and positioning based on available access to each electrical node
- Full reporting of placements including reason codes for inaccessible points
- Leading industry tester formats supported
- AOI & AXI tester programming
- Programs take into account the location of AOI/AXI machines on the line and components that should be placed up to that point



### Stencil design

SIEMENS
Ingenuity for life

- Automatically create stencils from product model
- Customizable rules and aperture properties
- Output to ODB++ or Gerber 274X



#### **Value-Add Services**



#### **❖ Valor Process Preparation deployment service**

- > Lean Process consulting Get the tools implemented and fine-tuned to YOUR environment
- Customization and fine tuning of machine shape auto-generation rules

#### Process automation

Leverage Valor Process Preparation's comprehensive API to streamline data flow from design to manufacturing

#### **❖** Manufacturing Cost Simulator & Quote Builder

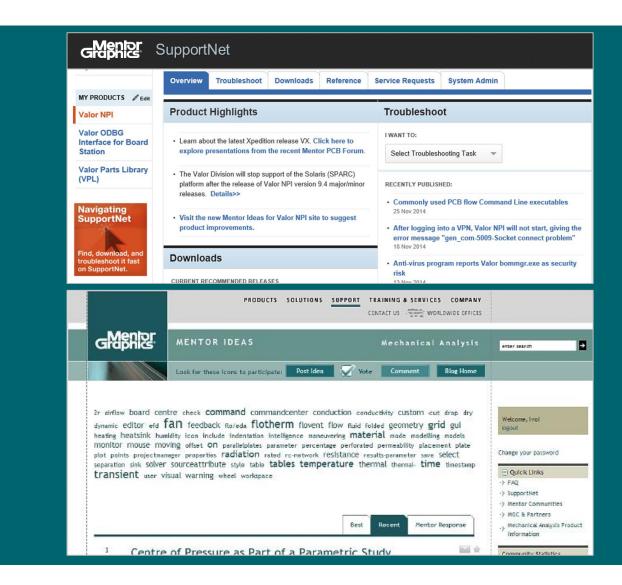
- Uses data available from Valor Process Prep. to generate accurate manufacturing cost simulation
- Based on BOM, factory cost model and design complexity
- > Optional: integration to 3<sup>rd</sup>-party component cost providers (e.g. SiliconExpert, DigiKey)

Design Complexity Factor R	ating 🔽					
1. Single sided						
2. Double sided						
3. For each 200 placements per side						
4. For each 5 BGA's per side (>0.8mm pitch and >25mm <sup>2</sup> )						
5. For each 3 uBGA's per side (<0.8mm pitch and <25mm <sup>2</sup> )						
6. > 8" in the X dimension						
7. > 8" in the Y dimension						
8. For each 2 LGA's per side						
9. For each 10 QFN's > 10mm <sup>2</sup> per side						
10. For each 5 QFN's < 10mm <sup>2</sup> per side						
11. For each 10 QPF's > 20mil pitch per side						
12. For each 5 QFP'S < 20mil pitch per side						
13. Finish consideration (Enig > HASL > Silver > OSP)						
14. RoHS consideration						
15. Layer count / copper weight						
16. Rigid flex PCB						
17. Press fit connectors (count / type)						
• 1-5 Easy						
6-10 Intermediate						
• 11-15 Difficult						
16+ Very Complex						
18. Component density (parts/square inch)						
Total						

### #1 in support

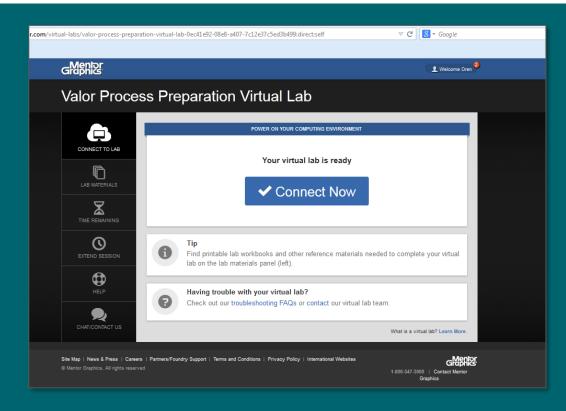


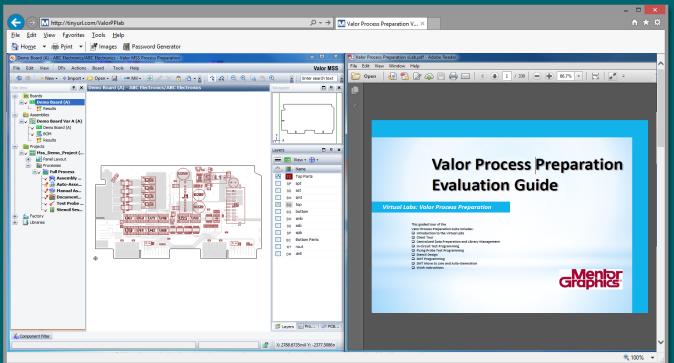
- SupportNet Open to all customers under support:
  - ✓ TechNotes
  - ✓ Best Practices
  - ✓ Tutorials
  - ✓ Quick Tips
  - ✓ Software distribution portal
  - ✓ Marketing Materials
  - Support requests from customers
- Mentor IDEAS:
  - Easy way to provide feedback and improvement suggestions
  - ✓ Vote to affect the priority of proposed enhancements



#### **Virtual lab**





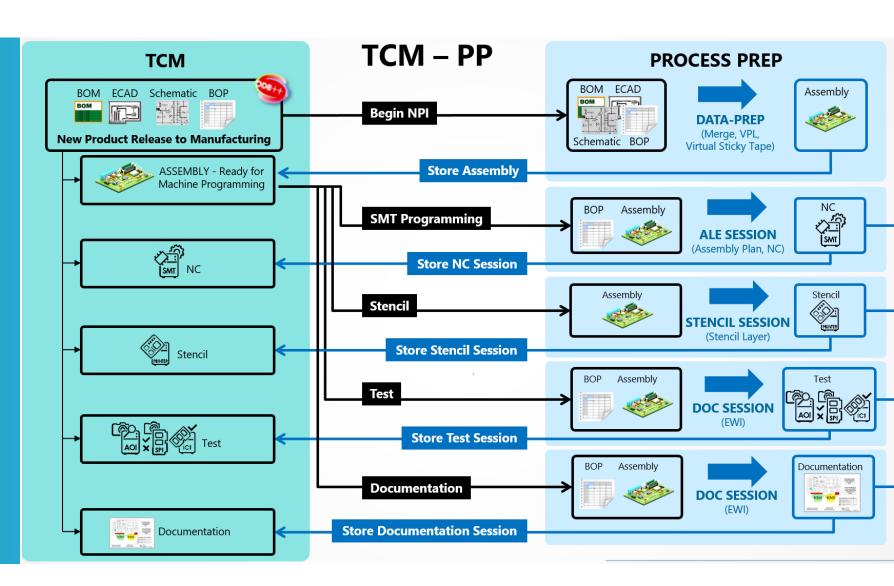


http://tinyurl.com/ValorPPlab

### Integrated to TCM as the process repository



- Increase manufacturing planning efficiency by leveraging Teamcenter Manufacturing as the overall process repository
- Prepare process plans for New product Introduction (NPI)
- Identify the impact of design changes on box build lines
- Deliver updated work instructions





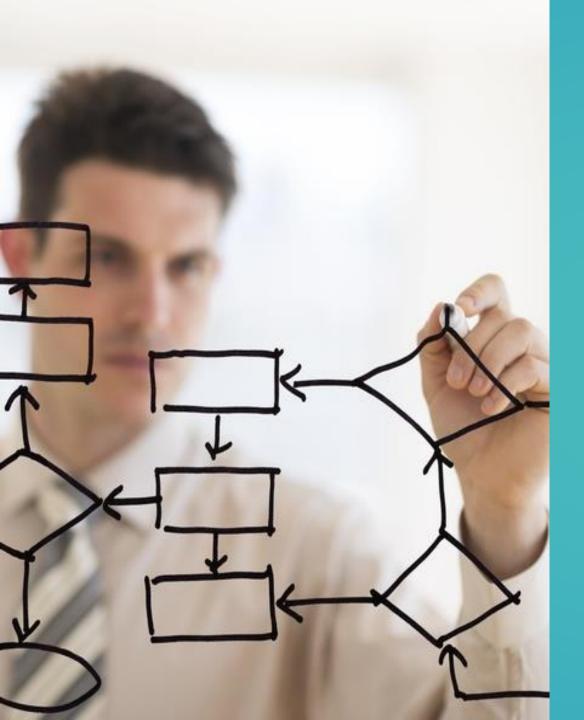
#### **BUSINESS CHALLENGE**

- Improve NPI time and cost
- Standardize engineering flow
- Improve global manufacturing flexibility

#### **BUSINESS RESULTS**

40% ENGINEERING TIME SAVED 2X FASTER NPI \$0.4M

ANNUAL
SAVING



# SIEMENS Ingenuity for life

## **Thank You**

